

Features

- Any frequency between 220.000001 MHz and 725 MHz, accurate to 6 decimal places
- LVPECL, LVDS and HCSL output signaling
- 0.1ps RMS phase jitter (random) for Ethernet applications
- Contact [SiTime](#) for frequency stability as low as ± 10 ppm
- Wide temperature range from -40°C to 85°C
Contact [SiTime](#) for higher temperature range options
- Industry-standard packages: 3.2 x 2.5, 7.0 x 5.0 mm
Contact [SiTime](#) for 5.0 x 3.2 mm package

Applications

- 100 GB Ethernet, SONET, SATA, SAS, Fibre Channel
- Telecom, networking, instrumentation, storage, servers



Electrical Characteristics

All Min and Max limits in the Electrical Characteristics tables are specified over temperature and rated operating voltage with standard output termination show in the termination diagrams. Typical values are at 25°C and nominal supply voltage.

Table 1. Electrical Characteristics – Common to LVPECL, LVDS and HCSL

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Frequency Range						
Output Frequency Range	f	220.000001	–	725	MHz	Accurate to 6 decimal places
Frequency Stability						
Frequency Stability	F_stab	-10	–	+10	ppm	Inclusive of initial tolerance, operating temperature, rated power supply voltage and load variations. Contact SiTime for ± 10 ppm.
		-20	–	+20	ppm	Inclusive of initial tolerance, operating temperature, rated power supply voltage and load variations
		-25	–	+25	ppm	
		-50	–	+50	ppm	
First Year Aging	F_aging1	–	± 1	–	ppm	At 25°C
Temperature Range						
Operating Temperature Range	T_use	-20	–	+70	$^{\circ}\text{C}$	Extended Commercial
		-40	–	+85	$^{\circ}\text{C}$	Industrial. Contact SiTime for higher temperature range options
Supply Voltage						
Supply Voltage	Vdd	2.97	3.30	3.63	V	
		2.70	3.00	3.30	V	
		2.52	2.80	3.08	V	
		2.25	2.50	2.75	V	
Input Characteristics						
Input Voltage High	VIH	70%	–	–	Vdd	Pin 1, OE
Input Voltage Low	VIL	–	–	30%	Vdd	Pin 1, OE
Input Pull-up Impedance	Z_in	–	100	–	k Ω	Pin 1, OE logic high or logic low
Output Characteristics						
Duty Cycle	DC	45	–	55	%	
Startup and OE Timing						
Startup Time	T_start	–	–	3.0	ms	Measured from the time Vdd reaches its rated minimum value.
OE Enable/Disable Time	T_oe	–	–	3.8	μs	f = 322.265652 MHz.

Table 2. Electrical Characteristics – LVPECL Specific

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Current Consumption						
Current Consumption	I _{dd}	–	–	94	mA	Excluding Load Termination Current, V _{dd} = 3.3V or 2.5V
OE Disable Supply Current	I _{OE}	–	–	63	mA	OE = Low
Output Disable Leakage Current	I _{leak}	–	0.15	–	μA	OE = Low
Maximum Output Current	I _{driver}	–	–	32	mA	Maximum average current drawn from OUT+ or OUT-
Output Characteristics						
Output High Voltage	VOH	V _{dd} -1.1	–	V _{dd} -0.7	V	See Figure 2
Output Low Voltage	VOL	V _{dd} -1.9	–	V _{dd} -1.5	V	See Figure 2
Output Differential Voltage Swing	V _{Swing}	1.2	1.6	2.0	V	See Figure 3
Rise/Fall Time	T _r , T _f	–	225	290	ps	20% to 80%, see Figure 2
Jitter						
RMS Phase Jitter (random)	T _{phj}	–	0.225	0.270	ps	f = 322.265625 MHz, Integration bandwidth = 12 kHz to 20 MHz, all V _{dds} , Includes spurs. 7.0 x 5.0 mm package.
		–	0.225	0.275	ps	f = 322.265625 MHz, Integration bandwidth = 12 kHz to 20 MHz, all V _{dds} , Includes spurs. 3.2 x 2.5 mm package.
		–	0.1	–	ps	f = 322.265625 MHz, IEEE802.3-2005 10GbE jitter mask integration bandwidth = 1.875 MHz to 20 MHz, Includes spurs, all V _{dds}
RMS Period Jitter ^[1]	T _{jitt}	–	1.0	1.6	ps	f = 322.265625 MHz, V _{DD} = 3.3V or 2.5V

Notes:

1. Measured according to JESD65B

Table 3. Electrical Characteristics – LVDS Specific

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Current Consumption						
Current Consumption	I _{dd}	–	–	89	mA	Excluding Load Termination Current, V _{dd} = 3.3V or 2.5V
OE Disable Supply Current	I _{OE}	–	–	67	mA	OE = Low
Output Disable Leakage Current	I _{leak}	–	0.15	–	μA	OE = Low
Output Characteristics						
Differential Output Voltage	VOD	250	–	455	mV	See Figure 4
VOD Magnitude Change	ΔVOD	–	–	50	mV	See Figure 4
Offset Voltage	VOS	1.125	–	1.375	V	See Figure 4
VOS Magnitude Change	ΔVOS	–	–	50	mV	See Figure 4
Rise/Fall Time	T _r , T _f	–	370	465	ps	Measured with 2 pF capacitive loading to GND, 20% to 80%, see Figure 4
Jitter						
RMS Phase Jitter (random)	T _{phj}	–	0.215	0.265	ps	f = 322.265625 MHz, Integration bandwidth = 12 kHz to 20 MHz, all V _{dds} , Includes spurs. 7.0 x 5.0 mm package.
		–	0.235	0.282	ps	f = 322.265625 MHz, Integration bandwidth = 12 kHz to 20 MHz, all V _{dds} , Includes spurs. 3.2 x 2.5 mm package.
		–	0.1	–	ps	f = 322.265625 MHz, IEEE802.3-2005 10GbE jitter mask integration bandwidth = 1.875 MHz to 20 MHz, Includes spurs, all V _{dds}
RMS Period Jitter ^[2]	T _{jitt}	–	0.92	1.6	ps	f = 322.265625 MHz, V _{DD} = 3.3V or 2.5V

Notes:

2. Measured according to JESD65B

Table 4. Electrical Characteristics – HCSL Specific

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Current Consumption						
Current Consumption	I _{dd}	–	–	97	mA	Excluding Load Termination Current, V _{dd} = 3.3V or 2.5V
OE Disable Supply Current	I _{OE}	–	–	63	mA	OE = Low
Output Disable Leakage Current	I _{leak}	–	0.15	–	μA	OE = Low
Maximum Output Current	I _{driver}	–	–	35	mA	Maximum average current drawn from OUT+ or OUT-
Output Characteristics						
Output High Voltage	VOH	0.60	–	0.90	V	See Figure 2
Output Low Voltage	VOL	-0.05	–	0.08	V	See Figure 2
Output Differential Voltage Swing	V _{Swing}	1.2	1.4	1.9	V	See Figure 3
Rise/Fall Time	Tr, Tf	–	360	470	ps	Measured with 2 pF capacitive loading to GND, 20% to 80%, see Figure 2
Jitter						
RMS Phase Jitter (random)	T _{phj}	–	0.215	0.270	ps	f = 322.265625 MHz, Integration bandwidth = 12 kHz to 20 MHz, all V _{dds} , Includes spurs. 7.0 x 5.0 mm package.
		–	0.225	0.275	ps	f = 322.265625 MHz, Integration bandwidth = 12 kHz to 20 MHz, all V _{dds} , Includes spurs. 3.2 x 2.5 mm package.
		–	0.1	–	ps	f = 322.265625 MHz, IEEE802.3-2005 10GbE jitter mask integration bandwidth = 1.875 MHz to 20 MHz, Includes spurs, all V _{dds}
RMS Period Jitter ^[3]	T _{jitt}	–	1.0	1.6	ps	f = 322.265625 MHz, V _{DD} = 3.3V or 2.5V

Notes:

3. Measured according to JESD65

Table 5. Pin Description

Pin	Map	Functionality	
1	OE/NC	Output Enable (OE)	H ^[4] : specified frequency output L: output is high impedance
		Non Connect (NC)	H or L or Open: No effect on output frequency or other device functions
2	NC	NA	No Connect; Leave it floating or connect to GND for better heat dissipation
3	GND	Power	VDD Power Supply Ground
4	OUT+	Output	Oscillator output
5	OUT-	Output	Complementary oscillator output
6	VDD	Power	Power supply voltage ^[5]

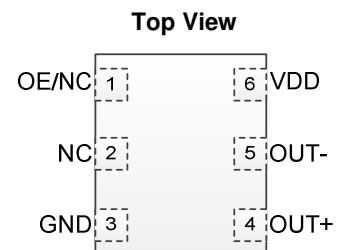


Figure 1. Pin Assignments

Notes:

4. In OE mode, a pull-up resistor of 10 kΩ or less is recommended if pin 1 is not externally driven.
5. A capacitor of value 0.1 μF or higher between V_{dd} and GND is required. An additional 10 μF capacitor between V_{dd} and GND is required for the best phase jitter performance

Table 6. Absolute Maximum Ratings

Attempted operation outside the absolute maximum ratings may cause permanent damage to the part. Actual performance of the IC is only guaranteed within the operational specifications, not at absolute maximum ratings.

Parameter	Min.	Max.	Unit
VDD	-0.5	4.0	V
VIH		VDD + 0.3V	V
VIL	-0.3		V
Storage Temperature	-65	150	°C
Maximum Junction Temperature		130	°C
Soldering Temperature (follow standard Pb-free soldering guidelines)		260	°C

Table 7. Thermal Considerations^[6]

Package	θ_{JA} , 4 Layer Board (°C/W)	θ_{JC} , Bottom (°C/W)
3225, 6-pin	80	30
7050, 6-pin	52	19

Notes:

6. Refer to JESD51 for θ_{JA} and θ_{JC} definitions, and reference layout used to determine the θ_{JA} and θ_{JC} values in the above table.

Table 8. Maximum Operating Junction Temperature^[7]

Max Operating Temperature (ambient)	Maximum Operating Junction Temperature
70°C	95°C
85°C	110°C

Notes:

7. Datasheet specifications are not guaranteed if junction temperature exceeds the maximum operating junction temperature.

Table 9. Environmental Compliance

Parameter	Test Conditions	Value	Unit
Mechanical Shock Resistance	MIL-STD-883F, Method 2002	10,000	<i>g</i>
Mechanical Vibration Resistance	MIL-STD-883F, Method 2007	70	<i>g</i>
Soldering Temperature (follow standard Pb free soldering guidelines)	MIL-STD-883F, Method 2003	260	°C
Moisture Sensitivity Level	MSL1 @ 260°C		
Electrostatic Discharge (HBM)	HBM, JESD22-A114	2,000	V
Charge-Device Model ESD Protection	JESD220C101	750	V
Latch-up Tolerance	JESD78 Compliant		

Waveform Diagrams

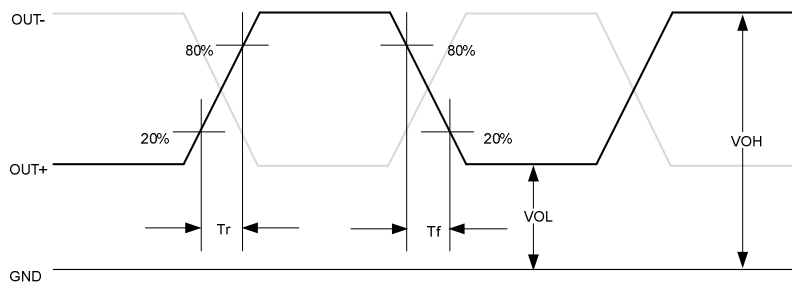


Figure 2. LVPECL/HCSL Voltage Levels per Differential Pin (OUT+/OUT-)

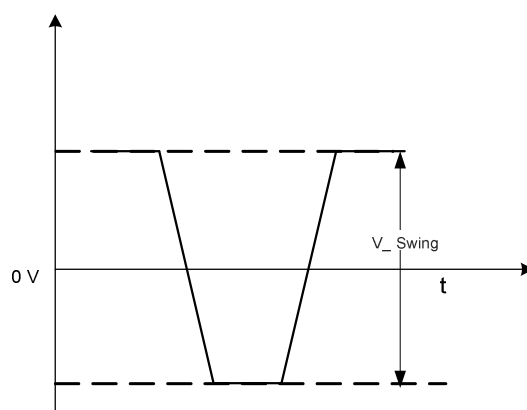


Figure 3. LVPECL/HCSL Voltage Levels across Differential Pair

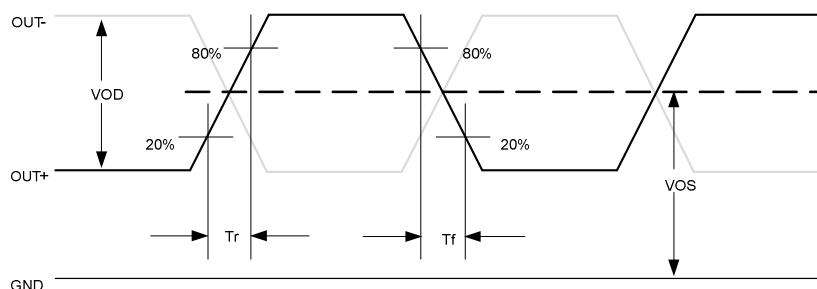


Figure 4. LVDS Voltage Levels per Differential Pin (OUT+/OUT-)

Termination Diagrams

LVPECL:

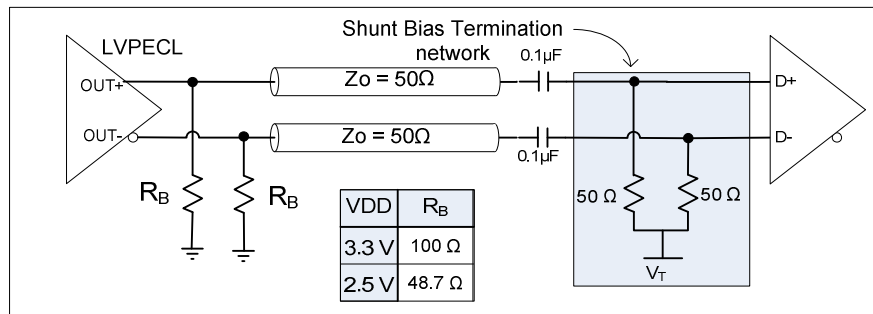


Figure 5. LVPECL with AC-coupled termination

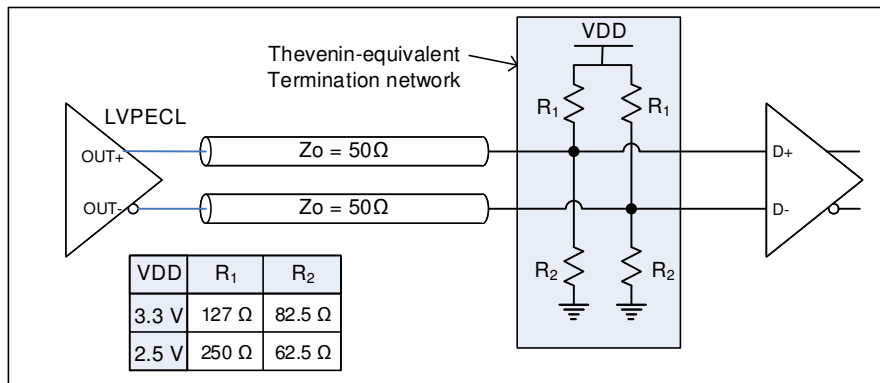


Figure 6. LVPECL DC-coupled load termination with Thevenin equivalent network

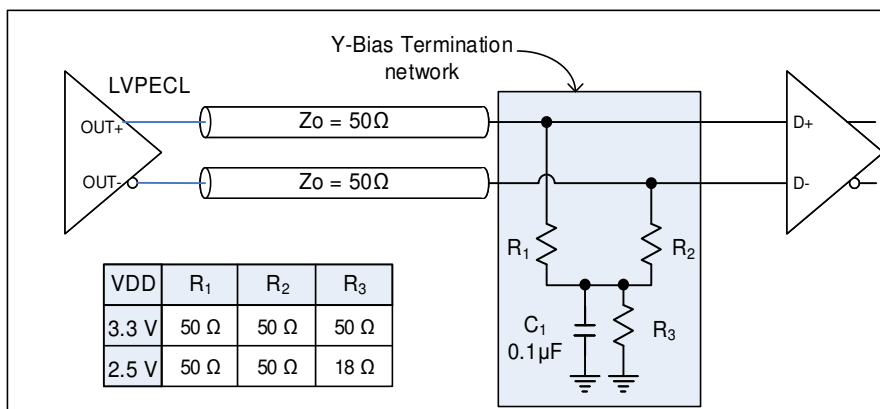


Figure 7. LVPECL with Y-Bias termination

Termination Diagrams (Continued)

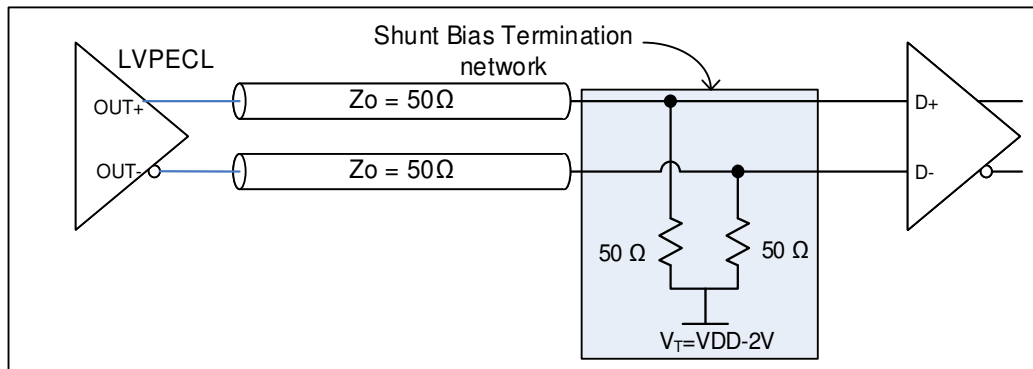


Figure 8. LVPECL with DC-coupled parallel shunt load termination

Termination Diagrams (Continued)

LVDS:

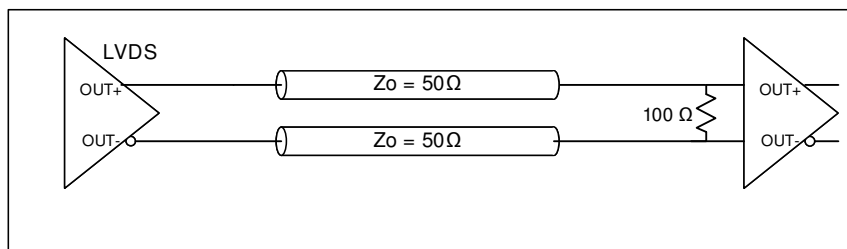


Figure 9. LVDS single DC termination at the load

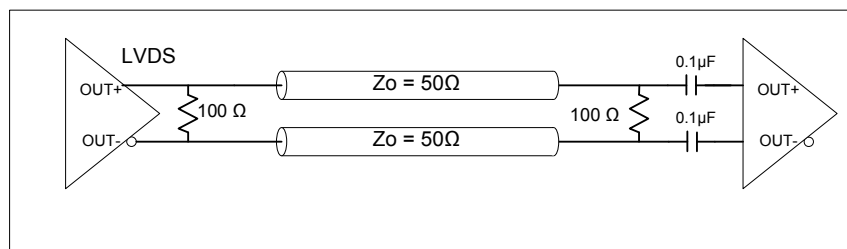


Figure 10. LVDS double AC termination with capacitor close to the load

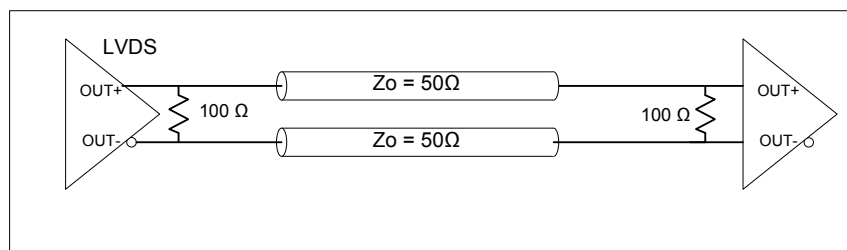


Figure 11. LVDS double DC termination

Termination Diagrams (Continued)

HCSL:

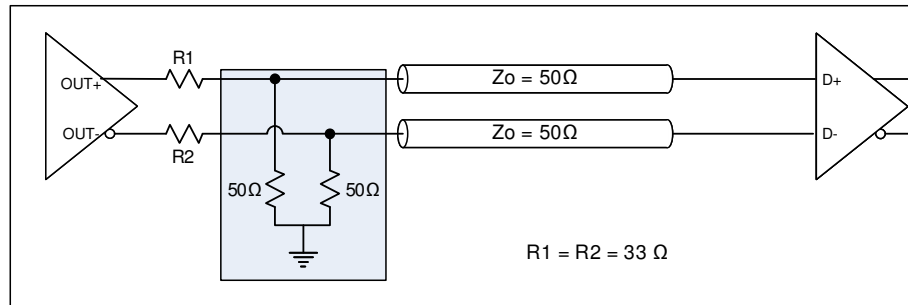


Figure 12. HCSL interface termination

Dimensions and Patterns

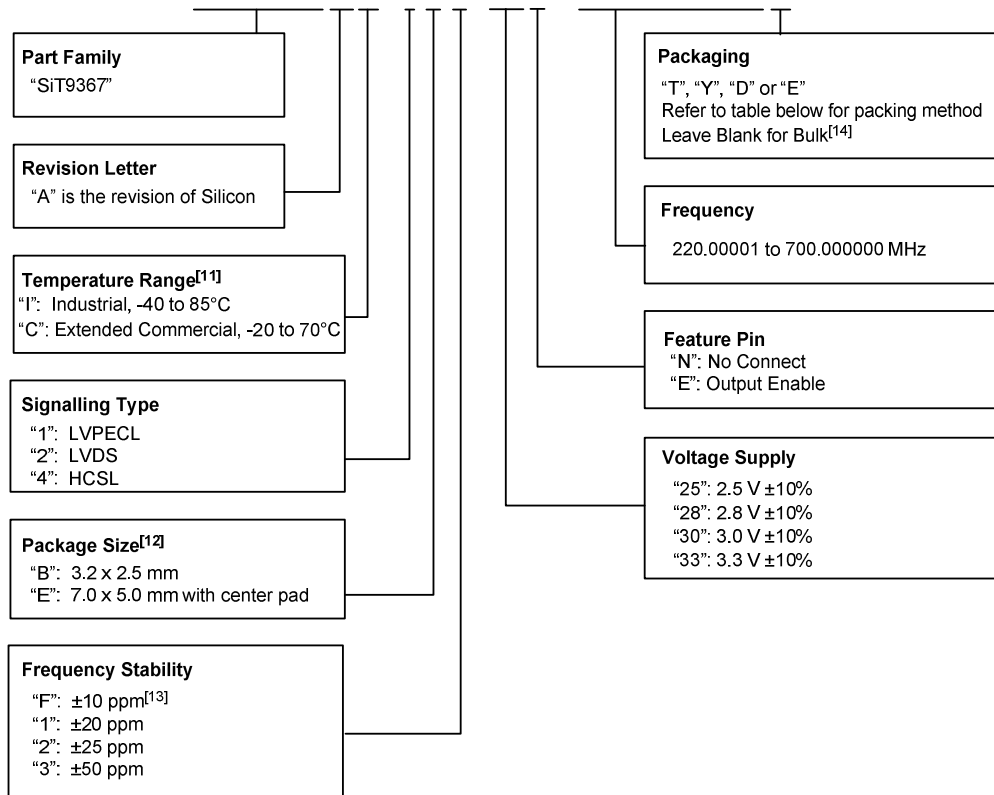
Package Size – Dimensions (Unit: mm) ^[8]	Recommended Land Pattern (Unit: mm) ^[9]																																																					
<p>3.2 x 2.5 x 0.75 mm</p> <table border="1"> <caption>Dimension Table</caption> <thead> <tr> <th></th> <th>Symbol</th> <th>Min</th> <th>Nom</th> <th>Max</th> </tr> </thead> <tbody> <tr> <td>TOTAL THICKNESS</td> <td>A</td> <td>0.800</td> <td>0.850</td> <td>0.900</td> </tr> <tr> <td rowspan="2">BODY SIZE</td> <td>X</td> <td>D</td> <td>2.400</td> <td>2.500</td> <td>2.600</td> </tr> <tr> <td>Y</td> <td>E</td> <td>3.200</td> <td>3.200</td> <td>3.300</td> </tr> <tr> <td>LEAD PITCH</td> <td>e</td> <td colspan="3">1.100 BSC</td> </tr> <tr> <td>LEAD LENGTH</td> <td>L</td> <td>0.650</td> <td>0.700</td> <td>0.750</td> </tr> <tr> <td>LEAD WIDTH</td> <td>W</td> <td>0.550</td> <td>0.600</td> <td>0.650</td> </tr> </tbody> </table> <table border="1"> <tr> <td>6L QFN</td> <td>Package Outline</td> </tr> <tr> <td>3.2 x 2.5 x 0.75 mm</td> <td></td> </tr> <tr> <td>POD-38 Rev A</td> <td></td> </tr> </table>		Symbol	Min	Nom	Max	TOTAL THICKNESS	A	0.800	0.850	0.900	BODY SIZE	X	D	2.400	2.500	2.600	Y	E	3.200	3.200	3.300	LEAD PITCH	e	1.100 BSC			LEAD LENGTH	L	0.650	0.700	0.750	LEAD WIDTH	W	0.550	0.600	0.650	6L QFN	Package Outline	3.2 x 2.5 x 0.75 mm		POD-38 Rev A		<p>3.2 x 2.5 x 0.75 mm</p>											
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Notes:

8. Top Marking: Y denotes manufacturing origin and XXXX denotes manufacturing lot number. The value of "Y" will depend on the assembly location of the device.
9. A capacitor of value 0.1 μF or higher between Vdd and GND is required. An additional 10 μF capacitor between Vdd and GND is required for the best phase jitter performance
10. The center pad has no electrical function. Soldering down the center pad to the GND is recommended for best thermal dissipation, but is optional.

Ordering Information

SiT9367AC-1B2-33E322.265625T



Notes:

- 11. Contact [SiTime](#) for higher temperature range options
- 12. Contact [SiTime](#) for 5.0 x 3.2 mm package
- 13. Contact [SiTime](#) for ± 10 ppm option
- 14. Bulk is available for sampling only

Table 10. Ordering Codes for Supported Tape & Reel Packing Method

Device Size (mm x mm)	8 mm T&R (3ku)	8 mm T&R (1ku)	12 mm T&R (3ku)	12 mm T&R (1ku)	16 mm T&R (3ku)	16 mm T&R (1ku)
7.0 x 5.0	—	—	—	—	T	Y
3.2 x 2.5	D	E	T	Y	—	—

Table 11 .Revision History

Revision	Release Date	Change Summary
1.0	09/06/2017	Final release

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